AMENDMENTS TO THE CLAIMS

1. (Original) A leadframe to be used in a semiconductor device,

which comprises a plurality of parallel first leads and a plurality of parallel second leads,

wherein the pitch of the first leads is different from that of the second leads, and the first leads are joined end-to-end with the second leads.

2. (Original) The leadframe according to claim 1,

wherein at least either of the first leads or the second leads have their thickness reduced.

Claims 3 and 4 (Cancelled).

5. (Original) A semiconductor device using the leadframe according to claim 1.

6. (Original) An electronic equipment using the semiconductor device according to claim 5.

7. (New) A method for manufacturing a semiconductor device using a leadframe comprising the steps of:

providing a leadframe having at least two parallel first leads spaced by a first pitch and at least two parallel second leads spaced by a second pitch different than the first pitch and joined end-to-end with the first leads;

mounting a semiconductor element on the leadframe;

encapsulating the semiconductor element in a package; and

separating the second leads from the first leads.

8. (New) A method for manufacturing first and second different semiconductor devices from first and second identical leadframes comprising the steps of:

providing first and second leadframes each having at least two parallel first leads spaced by a first pitch and at least two parallel second leads spaced by a second pitch different than the

first pitch and joined end-to-end with the first leads;

mounting a first semiconductor element on the first leadframe;

mounting a second semiconductor element on the second leadframe;

encapsulating the first semiconductor in a first package;

encapsulating the second semiconductor in a second package different than the first package;

bending the at least two parallel second leads of the first leadframe at an angle to the at least two parallel first leads of the first leadframe; and

separating the at least two parallel second leads of the second leadframe from the at least two parallel first leads of the second leadframe.

9. (New) The method of claim 8 wherein:

said step of encapsulating the first semiconductor in a first package comprises the step of enclosing a first length of the at least two parallel first leads of the first leadframe in the first package; and

said step of encapsulating the second semiconductor in a second package comprises the step of enclosing a second length of the at least two parallel first leads of the second leadframe in the second package;

wherein the first length is greater than the second length.

10. (New) The method of claim 8 wherein the first package comprises a DIP package.

11. (New) The method of claim 8 wherein the second package comprises a SOP package.